



SOT449-2

plastic small outline package; 40 leads (J-bent); body width
10.16 mm

6 September 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SOJ40
Package type industry code	SOJ40
Package style descriptive code	SOJ
Package body material type	P (plastic)
JEDEC package outline code	MS-027
Mounting method type	S (surface mount)
Issue date	8-4-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	25.9	-	26.05	26.2	mm
E	package width	10	-	10.16	10.3	mm
A	seated height	-	-	3.76	3.76	mm
A ₂	package height	2.74	-	2.79	2.84	mm
n ₂	actual quantity of termination	-	-	40	-	



2. Package outline

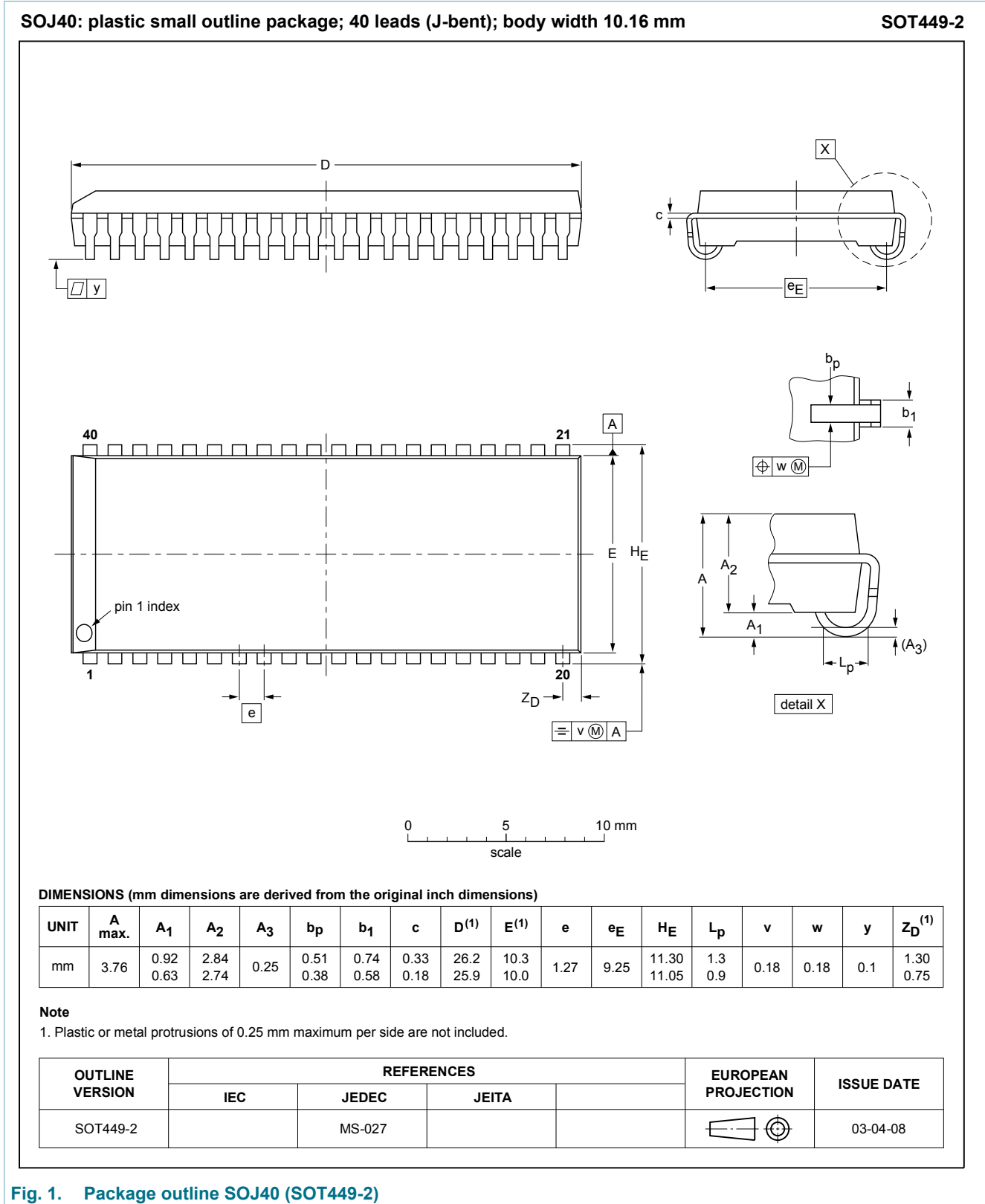


Fig. 1. Package outline SOJ40 (SOT449-2)

3. Soldering

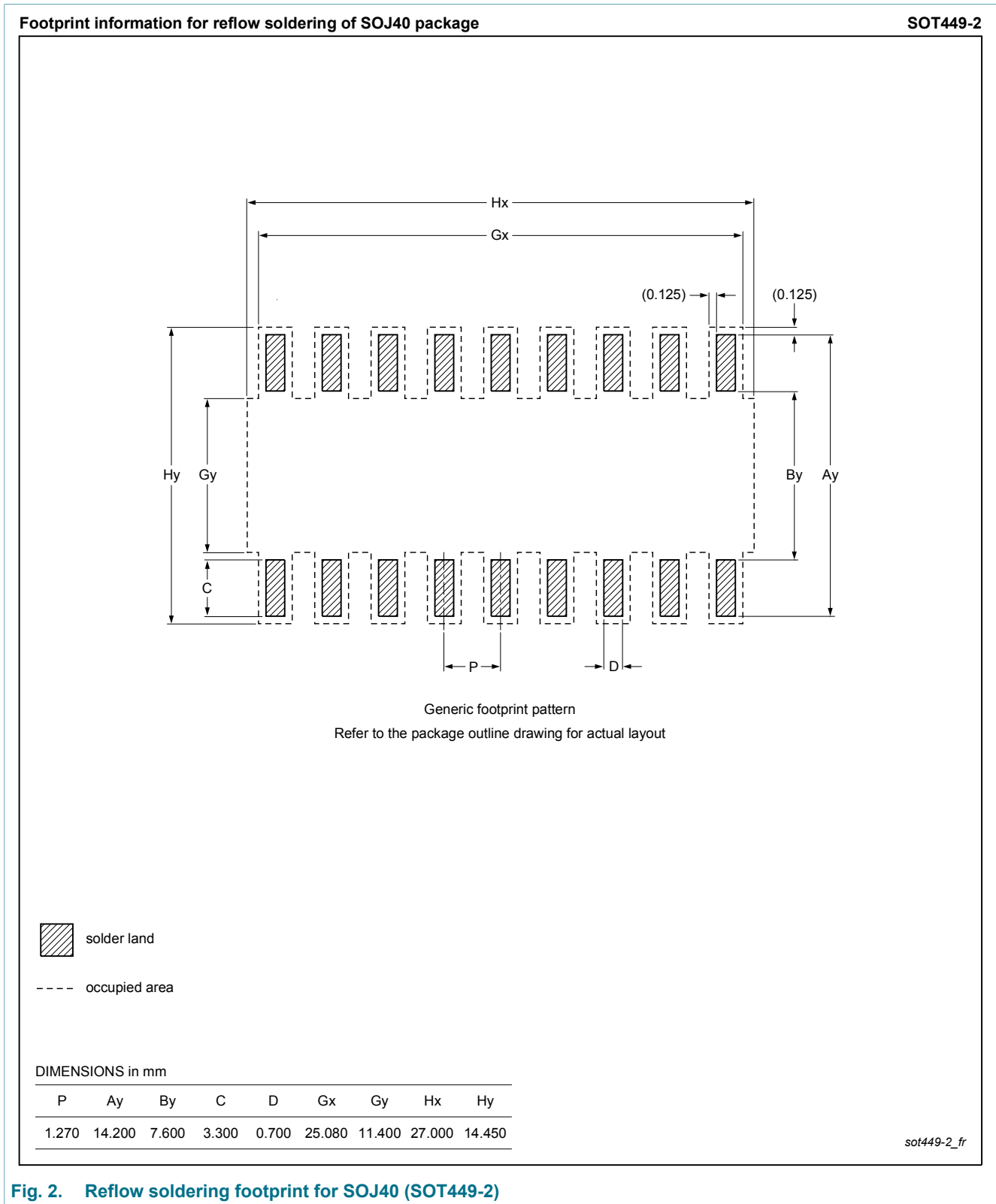


Fig. 2. Reflow soldering footprint for SOJ40 (SOT449-2)

4. Legal information

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